

Abstract of the Disclosure:

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In a semiconductor device having CSP structure, reinforcing pads are provided on corners of the mounting surface of the CSP body portion, and a plurality of solder balls are mounted on the reinforcing pads, respectively. In the reinforcing pad 21 of a square or 22 of a triangle, at least portions on which a part of solder balls positioned outer side among a plurality of the solder balls are mounted are hemmed to have roundness in line with outer sides of predetermined portions of planes of the solder balls 12 connected with the CSP body portion 11. Any acute angle portions are not produced in the hemmed portions. Mechanical stress is therefore not concentrated on the hemmed portions. As a result, remove of solder balls in the reinforcing pad can be reduced.

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